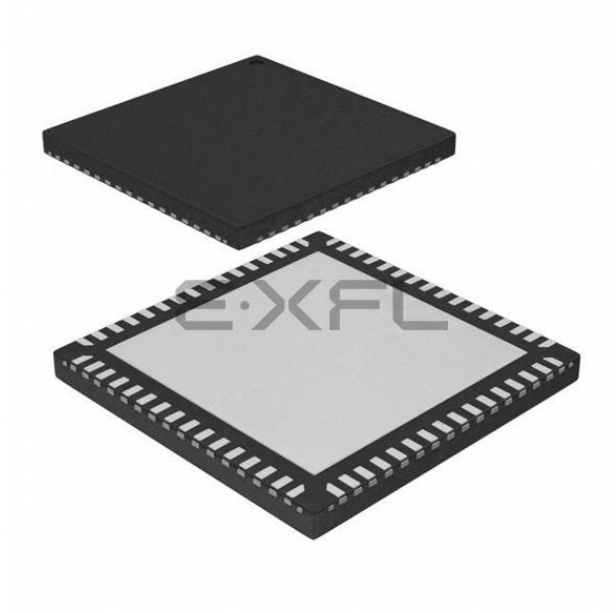

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	I²C, IrDA, Memory Card, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	47
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 11x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam4s8bb-mn

4.2.4 64-lead LQFP and QFN Pinout

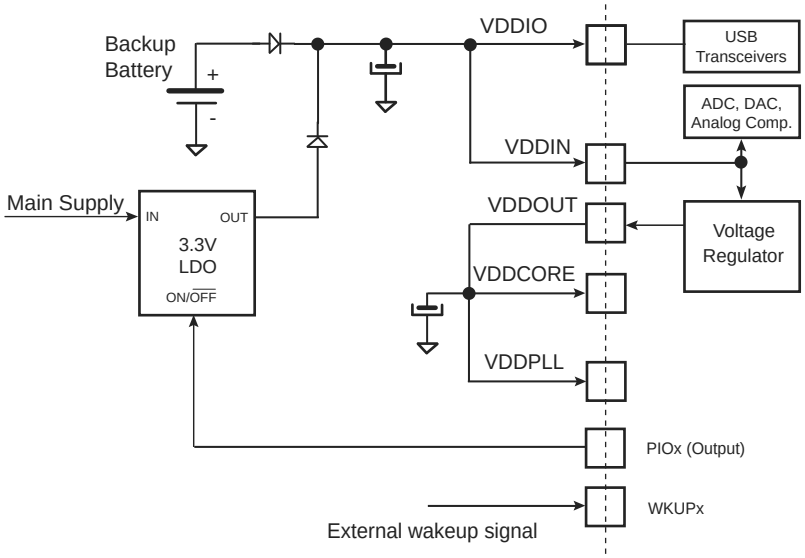
Table 4-4. 64-pin SAM4SD32/SD16/SA16/S16/S8/S4/S2 Pinout

1	ADVREF	17	GND	33	TDI/PB4	49	TDO/TRACESWO/PB5
2	GND	18	VDDIO	34	PA6/PGMNOE	50	JTAGSEL
3	PB0/AD4	19	PA16/PGMD4	35	PA5/PGMRDY	51	TMS/SWDIO/PB6
4	PB1/AD5	20	PA15/PGMD3	36	PA4/PGMNCMD	52	PA31
5	PB2/AD6	21	PA14/PGMD2	37	PA27/PGMD15	53	TCK/SWCLK/PB7
6	PB3/AD7	22	PA13/PGMD1	38	PA28	54	VDDCORE
7	VDDIN	23	PA24/PGMD12	39	NRST	55	ERASE/PB12
8	VDDOUT	24	VDDCORE	40	TST	56	DDM/PB10
9	PA17/PGMD5/AD0	25	PA25/PGMD13	41	PA29	57	DDP/PB11
10	PA18/PGMD6/AD1	26	PA26/PGMD14	42	PA30	58	VDDIO
11	PA21/PGMD9/AD8	27	PA12/PGMD0	43	PA3	59	PB13/DAC0
12	VDDCORE	28	PA11/PGMM3	44	PA2/PGMEN2	60	GND
13	PA19/PGMD7/AD2	29	PA10/PGMM2	45	VDDIO	61	XOUT/PB8
14	PA22/PGMD10/AD9	30	PA9/PGMM1	46	GND	62	XIN/PGMCK/PB9
15	PA23/PGMD11	31	PA8/XOUT32/PGMM0	47	PA1/PGMEN1	63	PB14/DAC1
16	PA20/PGMD8/AD3	32	PA7/XIN32/PGMNVALID	48	PA0/PGMEN0	64	VDDPLL

Note: The bottom pad of the QFN package must be connected to ground.

Figure 5-4 provides an example of the powering scheme when using a backup battery. Since the PIO state is preserved when in Backup mode, any free PIO line can be used to switch off the external regulator by driving the PIO line at low level (PIO is input, pull-up enabled after backup reset). External wake-up of the system can be from a push button or any signal. See Section 5.7 “Wake-up Sources” for further details.

Figure 5-4. Backup Battery



Note: The two diodes provide a “switchover circuit” (for illustration purpose) between the backup battery and the main supply when the system is put in backup mode.

Note: Restrictions:
For USB, VDDIO needs to be greater than 3.0V.
For ADC, DAC and Analog Comparator, VDDIN needs to be greater than 2.4V.

5.5 Active Mode

Active mode is the normal running mode with the core clock running from the fast RC oscillator, the main crystal oscillator or the PLLA. The Power Management Controller can be used to adapt the frequency and to disable the peripheral clocks.

5.6 Low-power Modes

The SAM4S has the following low-power modes: Backup mode, Wait mode and Sleep mode.

Note: The Wait For Event instruction (WFE) of the Cortex-M4 core can be used to enter any of the low-power modes, however, this may add complexity in the design of application state machines. This is due to the fact that the WFE instruction goes along with an event flag of the Cortex core (cannot be managed by the software application). The event flag can be set by interrupts, a debug event or an event signal from another processor. Since it is possible for an interrupt to occur just before the execution of WFE, WFE takes into account events that happened in the past. As a result, WFE prevents the device from entering Wait mode if an interrupt event has occurred.
Atmel has made provision to avoid using the WFE instruction. The workarounds to ease application design are as follows:
- For Backup mode, switch off the voltage regulator and configure the VROFF bit in the Supply Controller Control Register (SUPC_CR).
- For Wait mode, configure the WAITMODE bit in the PMC Clock Generator Main Oscillator Register of the Power Management Controller (PMC)
- For Sleep mode, use the Wait for Interrupt (WFI) instruction.

Complete information is available in Table 5-1 “Low-power Mode Configuration Summary".

highest number register using the highest memory address. If the writeback suffix is specified, the value of *Rn* + 4 * (*n*-1) is written back to *Rn*.

For LDMDB, LDMEA, STMDB, and STMFD the memory addresses used for the accesses are at 4-byte intervals ranging from *Rn* to *Rn* - 4 * (*n*-1), where *n* is the number of registers in *reglist*. The accesses happen in order of decreasing register numbers, with the highest numbered register using the highest memory address and the lowest number register using the lowest memory address. If the writeback suffix is specified, the value of *Rn* - 4 * (*n*-1) is written back to *Rn*.

The PUSH and POP instructions can be expressed in this form. See “PUSH and POP” for details.

Restrictions

In these instructions:

- *Rn* must not be PC
- *reglist* must not contain SP
- In any STM instruction, *reglist* must not contain PC
- In any LDM instruction, *reglist* must not contain PC if it contains LR
- *reglist* must not contain *Rn* if the writeback suffix is specified.

When PC is in *reglist* in an LDM instruction:

- Bit[0] of the value loaded to the PC must be 1 for correct execution, and a branch occurs to this halfword-aligned address
- If the instruction is conditional, it must be the last instruction in the IT block.

Condition Flags

These instructions do not change the flags.

Examples

```
LDM     R8,{R0,R2,R9}      ; LDMIA is a synonym for LDM
STMDB   R1!,{R3-R6,R11,R12}
```

Incorrect Examples

```
STM     R5!,{R5,R4,R9} ; Value stored for R5 is unpredictable
LDM     R2, {}         ; There must be at least one register in the list
```

12.6.6 Multiply and Divide Instructions

The table below shows the multiply and divide instructions.

Table 12-21. Multiply and Divide Instructions

Mnemonic	Description
MLA	Multiply with Accumulate, 32-bit result
MLS	Multiply and Subtract, 32-bit result
MUL	Multiply, 32-bit result
SDIV	Signed Divide
SMLA[B,T]	Signed Multiply Accumulate (halfwords)
SMLAD, SMLADX	Signed Multiply Accumulate Dual
SMLAL	Signed Multiply with Accumulate (32 × 32 + 64), 64-bit result
SMLAL[B,T]	Signed Multiply Accumulate Long (halfwords)
SMLALD, SMLALDX	Signed Multiply Accumulate Long Dual
SMLAW[B|T]	Signed Multiply Accumulate (word by halfword)
SMLSD	Signed Multiply Subtract Dual
SMLSLD	Signed Multiply Subtract Long Dual
SMMLA	Signed Most Significant Word Multiply Accumulate
SMMLS, SMMLSR	Signed Most Significant Word Multiply Subtract
SMUAD, SMUADX	Signed Dual Multiply Add
SMUL[B,T]	Signed Multiply (word by halfword)
SMMUL, SMMULR	Signed Most Significant Word Multiply
SMULL	Signed Multiply (32x32), 64-bit result
SMULWB, SMULWT	Signed Multiply (word by halfword)
SMUSD, SMUSDX	Signed Dual Multiply Subtract
UDIV	Unsigned Divide
UMAAL	Unsigned Multiply Accumulate Accumulate Long (32 × 32 + 32 + 32), 64-bit result
UMLAL	Unsigned Multiply with Accumulate (32 × 32 + 64), 64-bit result
UMULL	Unsigned Multiply (32 × 32), 64-bit result

```
op{XY}{cond} RdLo, RdHi, Rn, Rm
op{X}{cond} RdLo, RdHi, Rn, Rm
```

where:

op — is one of:

MLAL Signed Multiply Accumulate Long.

SMLAL Signed Multiply Accumulate Long (halfwords, X and Y).

X and Y specify which halfword of the source registers *Rn* and *Rm* are used as the first and second multiply operand:

If *X* is B, then the bottom halfword, bits [15:0], of *Rn* is used.
If *X* is T, then the top halfword, bits [31:16], of *Rn* is used.

If *Y* is B, then the bottom halfword, bits [15:0], of *Rm* is used.
If *Y* is T, then the top halfword, bits [31:16], of *Rm* is used.

SMLALD Signed Multiply Accumulate Long Dual.

SMLALDX Signed Multiply Accumulate Long Dual Reversed.

If the *X* is omitted, the multiplications are bottom × bottom and top × top.

If *X* is present, the multiplications are bottom × top and top × bottom.

cond — is an optional condition code, see “Conditional Execution” .

RdHi, RdLo — are the destination registers.
RdLo is the lower 32 bits and *RdHi* is the upper 32 bits of the 64-bit integer.
For SMLAL, SMLALBB, SMLALBT, SMLALTB, SMLALTT, SMLALD and SMLALDX, they also hold the accumulating value.

Rn, Rm — are registers holding the first and second operands.

Operation

The SMLAL instruction:

- Multiplies the two’s complement signed word values from *Rn* and *Rm*.
- Adds the 64-bit value in *RdLo* and *RdHi* to the resulting 64-bit product.
- Writes the 64-bit result of the multiplication and addition in *RdLo* and *RdHi*.

The SMLALBB, SMLALBT, SMLALTB and SMLALTT instructions:

- Multiplies the specified signed halfword, Top or Bottom, values from *Rn* and *Rm*.
- Adds the resulting sign-extended 32-bit product to the 64-bit value in *RdLo* and *RdHi*.
- Writes the 64-bit result of the multiplication and addition in *RdLo* and *RdHi*.

The non-specified halfwords of the source registers are ignored.

The SMLALD and SMLALDX instructions interpret the values from *Rn* and *Rm* as four halfword two’s complement signed 16-bit integers. These instructions:

- If *X* is not present, multiply the top signed halfword value of *Rn* with the top signed halfword of *Rm* and the bottom signed halfword values of *Rn* with the bottom signed halfword of *Rm*.
- Or if *X* is present, multiply the top signed halfword value of *Rn* with the bottom signed halfword of *Rm* and the bottom signed halfword values of *Rn* with the top signed halfword of *Rm*.
- Add the two multiplication results to the signed 64-bit value in *RdLo* and *RdHi* to create the resulting 64-bit product.
- Write the 64-bit product in *RdLo* and *RdHi*.

Restrictions

In these instructions:

12.9.1.8 System Handler Priority Registers

The SCB_SHPR1–SCB_SHPR3 registers set the priority level, 0 to of the exception handlers that have configurable priority. They are byte-accessible.

The system fault handlers and the priority field and register for each handler are:

Table 12-33. System Fault Handler Priority Fields

Handler	Field	Register Description
Memory management fault (MemManage)	PRI_4	System Handler Priority Register 1
Bus fault (BusFault)	PRI_5	
Usage fault (UsageFault)	PRI_6	
SVCall	PRI_11	System Handler Priority Register 2
PendSV	PRI_14	System Handler Priority Register 3
SysTick	PRI_15	

Each PRI_N field is 8 bits wide, but the processor implements only bits [7:] of each field, and bits [:0] read as zero and ignore writes.

The table below shows the encodings for the TEX, C, B, and S access permission bits.

Table 12-36. TEX, C, B, and S Encoding

TEX	C	B	S	Memory Type	Shareability	Other Attributes
b000	0	0	x(1)	Strongly-ordered	Shareable	–
		1	x(1)	Device	Shareable	–
	1	0	0	Normal	Not shareable	Outer and inner write-through. No write allocate.
			1		Shareable	
		1	0	Normal	Not shareable	Outer and inner write-back. No write allocate.
			1		Shareable	
b001	0	0	0	Normal	Not shareable	Outer and inner noncacheable.
			1		Shareable	
		1	x(1)	Reserved encoding		–
	1	0	x(1)	Implementation defined attributes.		–
		1	0	Normal	Not shareable	Outer and inner write-back. Write and read allocate.
			1		Shareable	
b010	0	0	x(1)	Device	Not shareable	Nonshared Device.
		1	x(1)	Reserved encoding		–
	1	x(1)	x(1)	Reserved encoding		–
b1BB	A	A	0	Normal	Not shareable	Cached memory BB = outer policy, AA = inner policy.
			1		Shareable	

Note: 1. The MPU ignores the value of this bit.

Table 12-37 shows the cache policy for memory attribute encodings with a TEX value is in the range 4–7.

Table 12-37. Cache Policy for Memory Attribute Encoding

Encoding, AA or BB	Corresponding Cache Policy
00	Non-cacheable
01	Write back, write and read allocate
10	Write through, no write allocate
11	Write back, no write allocate

14.5.1 Reset Controller Control Register

Name: RSTC_CR

Address: 0x400E1400

Access: Write-only

31	30	29	28	27	26	25	24
KEY							
23	22	21	20	19	18	17	16
–	–	–	–	–	–	–	–
15	14	13	12	11	10	9	8
–	–	–	–	–	–	–	–
7	6	5	4	3	2	1	0
–	–	–	–	EXTRST	PERRST	–	PROCRST

- **PROCRST: Processor Reset**

0: No effect

1: If KEY is correct, resets the processor

- **PERRST: Peripheral Reset**

0: No effect

1: If KEY is correct, resets the peripherals

- **EXTRST: External Reset**

0: No effect

1: If KEY is correct, asserts the NRST pin

- **KEY: System Reset Key**

Value	Name	Description
0xA5	PASSWD	Writing any other value in this field aborts the write operation.

16.6.9 RTC Interrupt Enable Register

Name: RTC_IER

Address: 0x400E1480

Access: Write-only

31	30	29	28	27	26	25	24
–	–	–	–	–	–	–	–
23	22	21	20	19	18	17	16
–	–	–	–	–	–	–	–
15	14	13	12	11	10	9	8
–	–	–	–	–	–	–	–
7	6	5	4	3	2	1	0
–	–	TDERREN	CALEN	TIMEN	SECEN	ALREN	ACKEN

- **ACKEN: Acknowledge Update Interrupt Enable**

0: No effect.

1: The acknowledge for update interrupt is enabled.

- **ALREN: Alarm Interrupt Enable**

0: No effect.

1: The alarm interrupt is enabled.

- **SECEN: Second Event Interrupt Enable**

0: No effect.

1: The second periodic interrupt is enabled.

- **TIMEN: Time Event Interrupt Enable**

0: No effect.

1: The selected time event interrupt is enabled.

- **CALEN: Calendar Event Interrupt Enable**

0: No effect.

1: The selected calendar event interrupt is enabled.

- **TDERREN: Time and/or Date Error Interrupt Enable**

0: No effect.

1: The time and date error interrupt is enabled.

The supply monitor can also be enabled during one slow clock period on every one of either 32, 256 or 2048 slow clock periods, depending on the user selection. This is configured in the SMSMPL field in SUPC_SMMR.

Enabling the supply monitor for such reduced times divides the typical supply monitor power consumption by factors of 2, 16 and 128, respectively, if continuous monitoring of the VDDIO power supply is not required.

A supply monitor detection generates either a reset of the core power supply or a wake-up of the core power supply. Generating a core reset when a supply monitor detection occurs is enabled by setting the SMRSTEN bit in SUPC_SMMR.

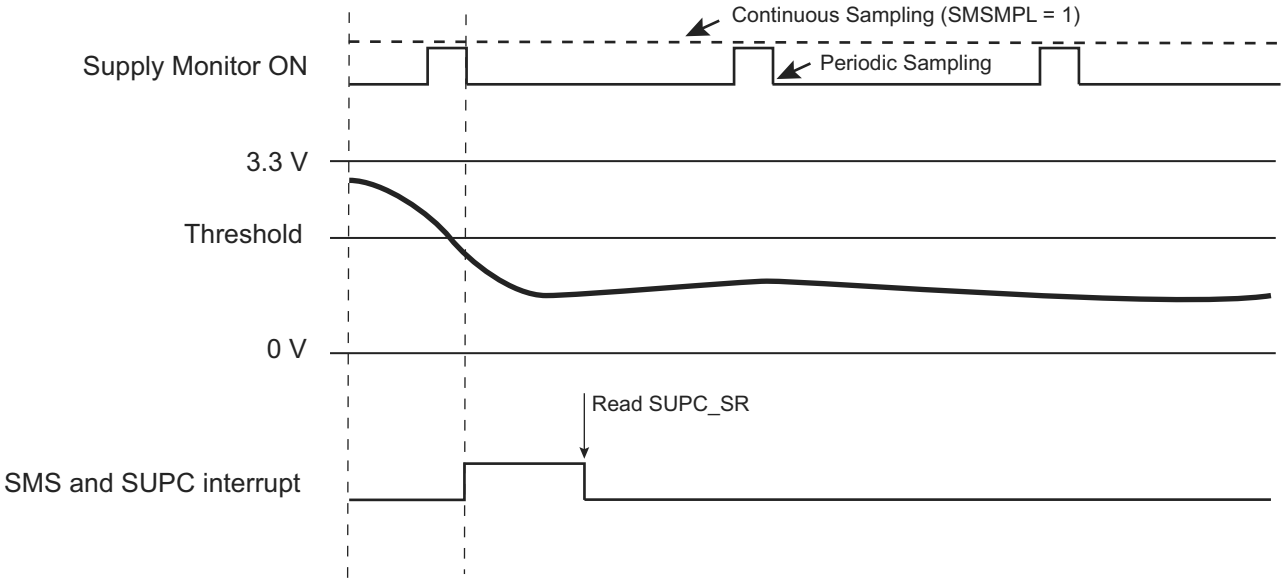
Waking up the core power supply when a supply monitor detection occurs can be enabled by setting the SMEN bit in the Wake-up Mode register (SUPC_WUMR).

The SUPC provides two status bits in the SUPC_SR for the supply monitor that determine whether the last wake-up was due to the supply monitor:

- The SMOS bit provides real-time information, updated at each measurement cycle or updated at each slow clock cycle, if the measurement is continuous.
- The SMS bit provides saved information and shows a supply monitor detection has occurred since the last read of SUPC_SR.

The SMS flag generates an interrupt if the SMIEN bit is set in SUPC_SMMR.

Figure 18-2. Supply Monitor Status Bit and Associated Interrupt



18.4.5 Backup Power Supply Reset

18.4.5.1 Raising the Backup Power Supply

When the backup voltage VDDIO rises, the RC oscillator is powered up and the zero-power power-on reset cell maintains its output low as long as VDDIO has not reached its target voltage. During this period, the SUPC is reset. When the VDDIO voltage becomes valid and the zero-power power-on reset signal is released, a counter is started for five slow clock cycles. This is the time required for the 32 kHz RC oscillator to stabilize.

After this time, the voltage regulator is enabled. The core power supply rises and the brownout detector provides the bodcore_in signal as soon as the core voltage VDDCORE is valid. This results in releasing the vddcore_nreset signal to the Reset Controller after the bodcore_in signal has been confirmed as being valid for at least one slow clock cycle.

20.4.2 Read Operations

An optimized controller manages embedded Flash reads, thus increasing performance when the processor is running in Thumb-2 mode by means of the 128- or 64-bit-wide memory interface.

The Flash memory is accessible through 8-, 16- and 32-bit reads.

As the Flash block size is smaller than the address space reserved for the internal memory area, the embedded Flash wraps around the address space and appears to be repeated within it.

The read operations can be performed with or without wait states. Wait states must be programmed in the field FWS in the Flash Mode register (EEFC_FMR). Defining FWS as 0 enables the single-cycle access of the embedded Flash. For mre details, refer to the section “Electrical Characteristics” of this datasheet.

20.4.2.1 128- or 64-bit Access Mode

By default, the read accesses of the Flash are performed through a 128-bit wide memory interface. It improves system performance especially when two or three wait states are needed.

For systems requiring only 1 wait state, or to focus on current consumption rather than performance, the user can select a 64-bit wide memory access via the bit EEFC_FMR.FAM.

For more details, refer to the section “Electrical Characteristics” of this datasheet.

20.4.2.2 Code Read Optimization

Code read optimization is enabled if the bit EEFC_FMR.SCOD is cleared.

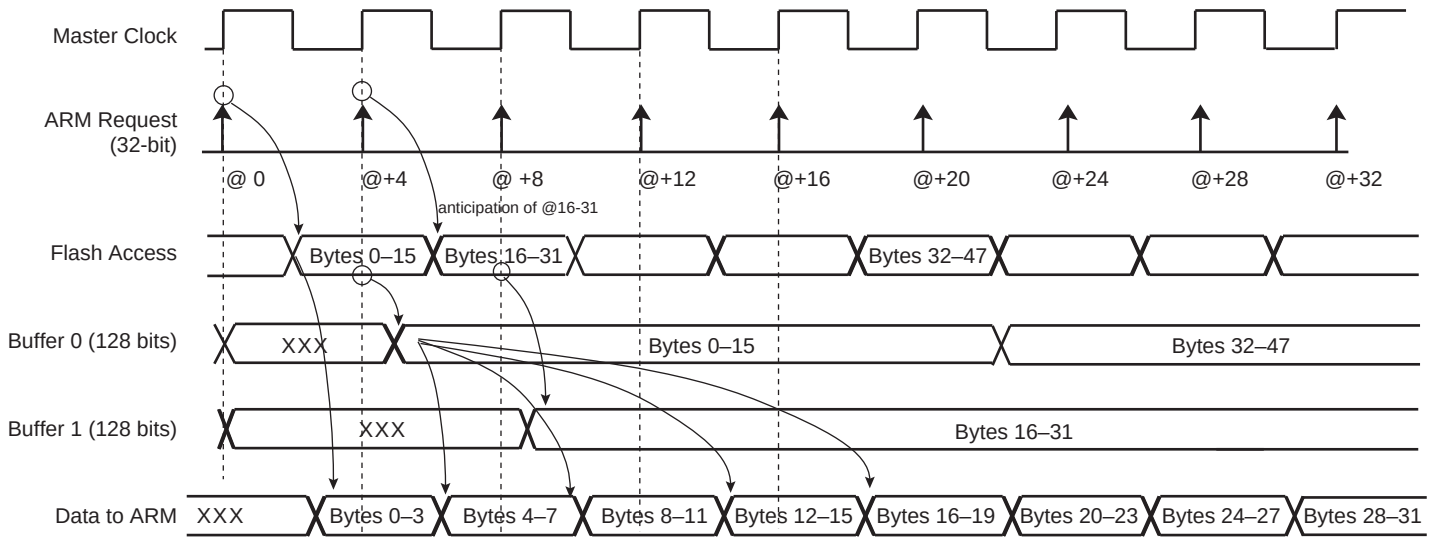
A system of 2 x 128-bit or 2 x 64-bit buffers is added in order to optimize sequential code fetch.

Note: Immediate consecutive code read accesses are not mandatory to benefit from this optimization.

The sequential code read optimization is enabled by default. If the bit EEFC_FMR.SCOD is set to 1, these buffers are disabled and the sequential code read is no longer optimized.

Another system of 2 x 128-bit or 2 x 64-bit buffers is added in order to optimize loop code fetch. Refer to Section 20.4.2.3 ”Code Loop Optimization” for more details.

Figure 20-3. Code Read Optimization for FWS = 0



Note: When FWS is equal to 0, all the accesses are performed in a single-cycle access.

- Flash Error: At the end of the programming, the EraseVerify or WriteVerify test of the Flash memory has failed.

The status of lock bits can be returned by the EEFC. The ‘Get Lock Bit’ sequence is the following:

1. Execute the ‘Get Lock Bit’ command by writing EEFC_FCR.FCMD with the GLB command. Field EEFC_FCR.FARG is meaningless.
2. Lock bits can be read by the software application in EEFC_FRR. The first word read corresponds to the 32 first lock bits, next reads providing the next 32 lock bits as long as it is meaningful. Extra reads to EEFC_FRR return 0.

For example, if the third bit of the first word read in EEFC_FRR is set, the third lock region is locked.

Two errors can be detected in EEFC_FSR after a programming sequence:

- Command Error: A bad keyword has been written in EEFC_FCR.
- Flash Error: At the end of the programming, the EraseVerify or WriteVerify test of the Flash memory has failed.

Note: Access to the Flash in read is permitted when a ‘Set Lock Bit’, ‘Clear Lock Bit’ or ‘Get Lock Bit’ command is executed.

20.4.3.5 GPNVM Bit

GPNVM bits do not interfere with the embedded Flash memory plane. For more details, refer to the section “Memories” of this datasheet.

The ‘Set GPNVM Bit’ sequence is the following:

1. Execute the ‘Set GPNVM Bit’ command by writing EEFC_FCR.FCMD with the SGPB command and EEFC_FCR.FARG with the number of GPNVM bits to be set.
2. When the GPNVM bit is set, the bit EEFC_FSR.FRDY rises. If an interrupt was enabled by setting the bit EEFC_FMR.FRDY, the interrupt line of the interrupt controller is activated.
3. The result of the SGPB command can be checked by running a ‘Get GPNVM Bit’ (GGPB) command.

Note: The value of the FARG argument passed together with SGPB command must not exceed the higher GPNVM index available in the product. Flash data content is not altered if FARG exceeds the limit. Command Error is detected only if FARG is greater than 8.

Two errors can be detected in EEFC_FSR after a programming sequence:

- Command Error: A bad keyword has been written in EEFC_FCR.
- Flash Error: At the end of the programming, the EraseVerify or WriteVerify test of the Flash memory has failed.

It is possible to clear GPNVM bits previously set. The ‘Clear GPNVM Bit’ sequence is the following:

1. Execute the ‘Clear GPNVM Bit’ command by writing EEFC_FCR.FCMD with the CGPB command and EEFC_FCR.FARG with the number of GPNVM bits to be cleared.
2. When the clear completes, the bit EEFC_FSR.FRDY rises. If an interrupt has been enabled by setting the bit EEFC_FMR.FRDY, the interrupt line of the interrupt controller is activated.

Note: The value of the FARG argument passed together with CGPB command must not exceed the higher GPNVM index available in the product. Flash data content is not altered if FARG exceeds the limit. Command Error is detected only if FARG is greater than 8.

Two errors can be detected in EEFC_FSR after a programming sequence:

- Command Error: A bad keyword has been written in EEFC_FCR.
- Flash Error: At the end of the programming, the EraseVerify or WriteVerify test of the Flash memory has failed.

The status of GPNVM bits can be returned by the EEFC. The sequence is the following:

Figure 26-20. TDF Optimization Disabled (TDF Mode = 0): TDF wait states between 2 read accesses on different chip selects

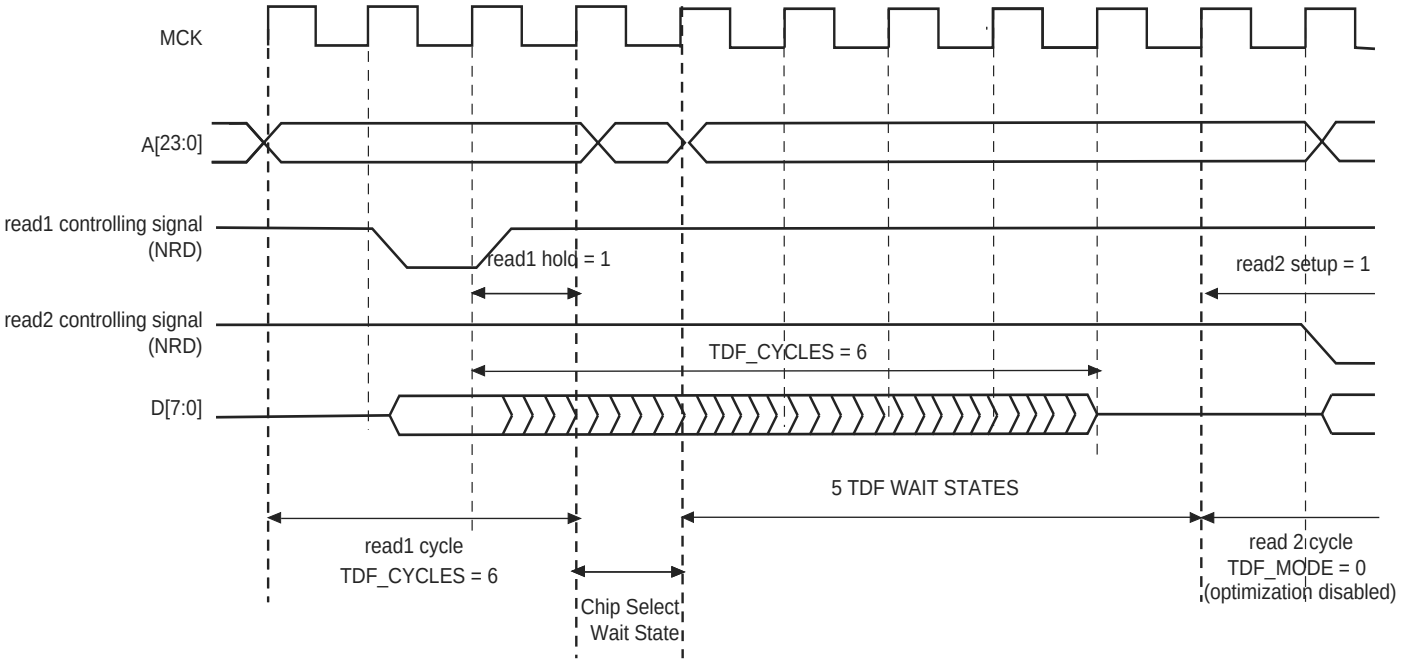
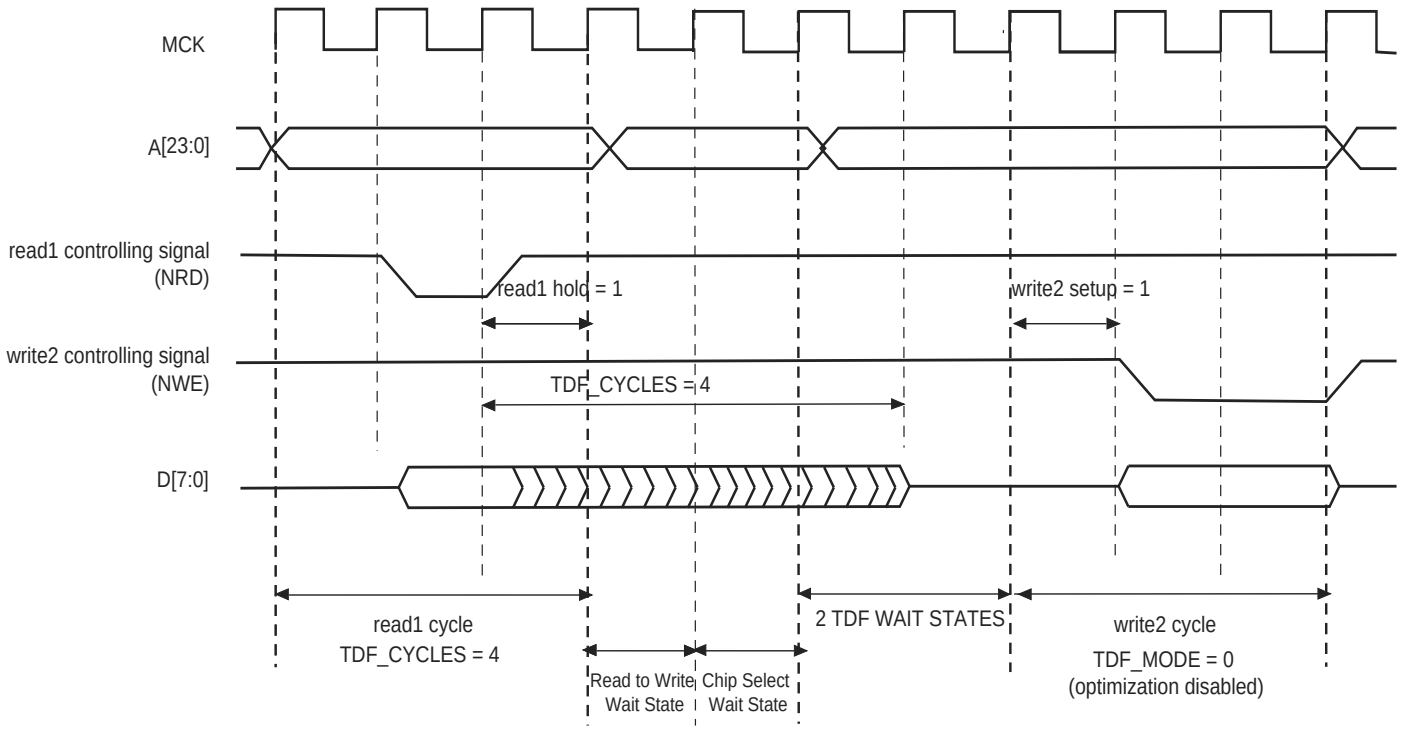


Figure 26-21. TDF Mode = 0: TDF wait states between a read and a write access on different chip selects



30. Chip Identifier (CHIPID)

30.1 Description

Chip Identifier (CHIPID) registers permit recognition of the device and its revision. These registers provide the sizes and types of the on-chip memories, as well as the set of embedded peripherals.

Two CHIPID registers are embedded: Chip ID Register (CHIPID_CIDR) and Chip ID Extension Register (CHIPID_EXID). Both registers contain a hard-wired value that is read-only.

The CHIPID_CIDR contains the following fields:

- VERSION: Identifies the revision of the silicon
- EPROC: Indicates the embedded ARM processor
- NVPTYP and NVPSIZ: Identify the type of embedded non-volatile memory and the size
- SRAMSIZ: Indicates the size of the embedded SRAM
- ARCH: Identifies the set of embedded peripherals
- EXT: Shows the use of the extension identifier register

The CHIPID_EXID register is device-dependent and reads 0 if CHIPID_CIDR.EXT = 0.

Table 31-5. Register Mapping (Continued)

Offset	Register	Name	Access	Reset
0x0154	Parallel Capture Interrupt Enable Register	PIO_PCIER	Write-only	–
0x0158	Parallel Capture Interrupt Disable Register	PIO_PCIDR	Write-only	–
0x015C	Parallel Capture Interrupt Mask Register	PIO_PCIMR	Read-only	0x00000000
0x0160	Parallel Capture Interrupt Status Register	PIO_PCISR	Read-only	0x00000000
0x0164	Parallel Capture Reception Holding Register	PIO_PCRHR	Read-only	0x00000000
0x0168–0x018C	Reserved for PDC Registers	–	–	–

Notes:
1. Reset value depends on the product implementation.
2. PIO_ODSR is Read-only or Read/Write depending on PIO_OWSR I/O lines.
3. Reset value of PIO_PDSR depends on the level of the I/O lines. Reading the I/O line levels requires the clock of the PIO Controller to be enabled, otherwise PIO_PDSR reads the levels present on the I/O line at the time the clock was disabled.
4. PIO_ISR is reset at 0x0. However, the first read of the register may read a different value as input changes may have occurred.
5. If an offset is not listed in the table it must be considered as reserved.

36.7.1 USART Control Register

Name: US_CR

Address: 0x40024000 (0), 0x40028000 (1)

Access: Write-only

31	30	29	28	27	26	25	24
–	–	–	–	–	–	–	–

23	22	21	20	19	18	17	16
–	–	–	–	RTSDIS	RTSEN	DTRDIS	DTREN

15	14	13	12	11	10	9	8
RETTO	RSTNACK	RSTIT	SENDA	STTTO	STPBRK	STTBRK	RSTSTA

7	6	5	4	3	2	1	0
TXDIS	TXEN	RXDIS	RXEN	RSTTX	RSTRX	–	–

For SPI control, see Section 36.7.2 ”USART Control Register (SPI_MODE)”.

- **RSTRX: Reset Receiver**

0: No effect.

1: Resets the receiver.

- **RSTTX: Reset Transmitter**

0: No effect.

1: Resets the transmitter.

- **RXEN: Receiver Enable**

0: No effect.

1: Enables the receiver, if RXDIS is 0.

- **RXDIS: Receiver Disable**

0: No effect.

1: Disables the receiver.

- **TXEN: Transmitter Enable**

0: No effect.

1: Enables the transmitter if TXDIS is 0.

- **TXDIS: Transmitter Disable**

0: No effect.

1: Disables the transmitter.

- **RSTSTA: Reset Status Bits**

0: No effect.

1: Resets the status bits PARE, FRAME, OVRE, MANERR and RXBRK in US_CSR.

36.7.4 USART Mode Register (SPI_MODE)

Name: US_MR (SPI_MODE)

Address: 0x40024004 (0), 0x40028004 (1)

Access: Read/Write

31	30	29	28	27	26	25	24
–	–	–	–	–	–	–	–

23	22	21	20	19	18	17	16
–	–	–	WRDBT	–	CLKO	–	CPOL

15	14	13	12	11	10	9	8
–	–	–	–	–	–	–	CPHA

7	6	5	4	3	2	1	0
CHRL		USCLKS		USART_MODE			

This configuration is relevant only if USART_MODE = 0xE or 0xF in the USART Mode Register.
This register can only be written if the WPEN bit is cleared in the USART Write Protection Mode Register.

- **USART_MODE: USART Mode of Operation**

Value	Name	Description
0xE	SPI_MASTER	SPI master
0xF	SPI_SLAVE	SPI Slave

- **USCLKS: Clock Selection**

Value	Name	Description
0	MCK	Peripheral clock is selected
1	DIV	Peripheral clock divided (DIV=8) is selected
3	SCK	Serial Clock SLK is selected

- **CHRL: Character Length**

Value	Name	Description
3	8_BIT	Character length is 8 bits

- **CPHA: SPI Clock Phase**
  – Applicable if USART operates in SPI mode (USART_MODE = 0xE or 0xF):

0: Data is changed on the leading edge of SPCK and captured on the following edge of SPCK.

1: Data is captured on the leading edge of SPCK and changed on the following edge of SPCK.

CPHA determines which edge of SPCK causes data to change and which edge causes data to be captured. CPHA is used with CPOL to produce the required clock/data relationship between master and slave devices.

- **CPOL: SPI Clock Polarity**

Applicable if USART operates in SPI mode (slave or master, USART_MODE = 0xE or 0xF):

0: The inactive state value of SPCK is logic level zero.

1: The inactive state value of SPCK is logic level one.

37.6.10 Waveform Mode

Waveform mode is entered by setting the TC_CMRx.WAVE bit.

In Waveform mode, the TC channel generates one or two PWM signals with the same frequency and independently programmable duty cycles, or generates different types of one-shot or repetitive pulses.

In this mode, TIOA is configured as an output and TIOB is defined as an output if it is not used as an external event (EEVT parameter in TC_CMR).

Figure 37-6 shows the configuration of the TC channel when programmed in Waveform operating mode.

37.6.11 Waveform Selection

Depending on the WAVSEL parameter in TC_CMR, the behavior of TC_CV varies.

With any selection, TC_RA, TC_RB and TC_RC can all be used as compare registers.

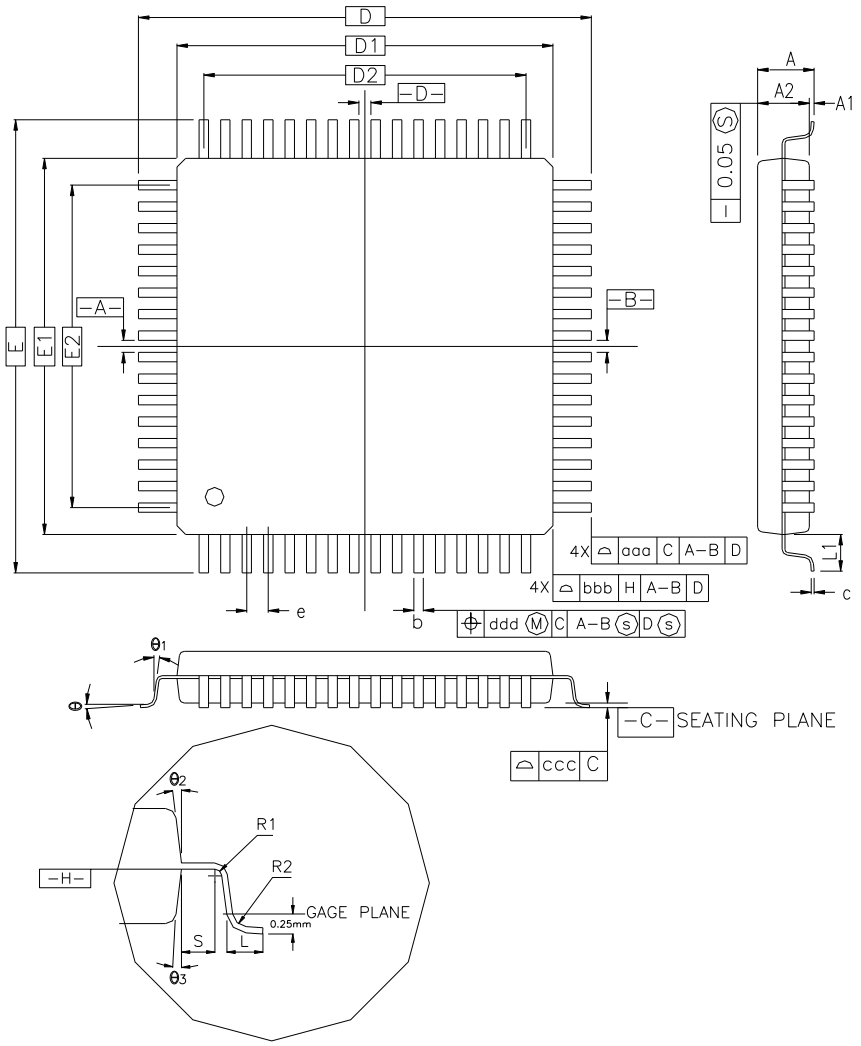
RA Compare is used to control the TIOA output, RB Compare is used to control the TIOB output (if correctly configured) and RC Compare is used to control TIOA and/or TIOB outputs.

45. Mechanical Characteristics

All packages of the SAM4S devices respect the recommendations of the NEMI User Group.

45.1 100-lead LQFP Mechanical Characteristics

Figure 45-1. 100-lead LQFP Package Mechanical Drawing



CONTROL DIMENSIONS ARE IN MILLIMETERS

SYMBOL	MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	—	—	1.60	—	—	0.063
A_1	0.05	—	0.15	0.002	—	0.006
A_2	1.35	1.40	1.45	0.053	0.055	0.057
D	16.00 BSC.			0.630 BSC.		
D_1	14.00 BSC.			0.551 BSC.		
E	16.00 BSC.			0.630 BSC.		
E_1	14.00 BSC.			0.551 BSC.		
R_2	0.08	—	0.20	0.003	—	0.008
R_1	0.08	—	—	0.003	—	—
θ	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	—	—	0°	—	—
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	—	0.20	0.004	—	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L_1	1.00 REF			0.039 REF		
S	0.20	—	—	0.008	—	—
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	12.00			0.472		
E2	12.00			0.472		
TOLERANCES OF FORM AND POSITION						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Note : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026 for additional information.

Table 45-1. Device and LQFP Package Maximum Weight

SAM4S	800	mg

Table 45-2. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	e3

Table 45-3. LQFP Package Characteristics

Moisture Sensitivity Level	3

Table 49-5. SAM4S Datasheet Rev. 11100G Revision History

Doc. Date	Changes
27-May-14	Table 3-1 ”Signal Description List”: WKUP[15:0] voltage reference type added.
	In Figure 5-4 “Backup Battery”, modified ADC, DAC, Analog Comparator Supply from 2.0V to 2.4V
	Modified Section 6.5 “ERASE Pin”.
	Modified bullet list on use of erase commands depending on sector size in Section 8.1.3.1 “Flash Overview”
	Modified Section 8.1.3.5 “Security Bit”, Section 8.1.3.11 “GPNVM Bits” and Section 8.1.4 “Boot Strategies”.
	Section 24. “Boot Program” Section 24.5.4 “In Application Programming (IAP) Feature”: 5th sentence: added “...the EFC number...”
	Section 29. “Power Management Controller (PMC)” Section 29.17.9 “PMC Clock Generator PLLA Register”: Min value for bit MULA corrected to 4 from 7. Section 29.17.10 “PMC Clock Generator PLLB Register”: Min value for bit MULB corrected to 4 from 1.
	Section 44. “Electrical Characteristics” Added Table 44-24 ”Typical Power Consumption on VDDCORE (VDDIO = 3.3V, TA = 25°C)”. Table 44-73 ”AC Flash Characteristics”: Added parameter Erase Pin Assertion Time.
	Section 48. “Errata” Added Section Issue: and Section Issue: “Incorrect Flash Read May Occur Depending on VDDIO Voltage and Flash Wait State”.